



Material Content Data Sheet

Umbrella Spec	IsoPACK™ 54						
Date	2012-03-19		RoHS compliant		Yes		
Revision	3.0						
Construction element	Material group	Materials	CAS-Nr. if applicable	Average mass [%]*	Sum [%]	Traces	Comment
chip	inorganic material	silicon	7440-21-3	0,32	0,32		
Base plate and substrate including metallisation	non noble metal	copper	7440-50-8	50,30	55,24		
	inorganic material	aluminium oxid	1344-28-1	1,70			
	non noble metal	tin	7440-31-5	2,98			
	noble metal	silver	7440-22-4	0,11			
	non noble metal	nickel	7440-02-0	0,15			
wire	non noble metal	aluminium	7429-90-5	0,26	0,26		
encapsulation	polymers	silicone gel		5,80	5,80		
housing	polymers	PBT		15,80	27,69		
	inorganic material	antimonytrioxide	1309-64-4	1,66			
	plastics	brominated resin		1,14			
	plastics	chlorinated resin		0,78			
	inorganic material	silicondioxide / glasfiber		8,31			
lead, finish and plating	non noble metal	copper	7440-50-8	5,25	10,65		
	ferrous metal	steel		5,40			
	non noble metal	zinc	7440-66-6				X
	non noble metal	tin	7440-31-5				X
	noble metal	silver	7440-22-4				X
	non noble metal	nickel	7440-02-0				X
deviation	<25%			Sum in total	100,0		

Weight range of product	305
Fluctuation margin	<25%

*) related to component weight

**) Weight of particular product, see technical product information

Important Remarks:

- 1) This document provides full declaration of all materials present in Infineon products above a threshold of 0,1 % b.w. (1000 ppm).
- 2) Trace concentrations (i.e. < 0,1 % b.w) present in products are marked with an "X" as far as they represent substances-of-concern.
A list of substances-of-concern can be found at <http://www.infineon.com/soc>.
- 3) All statements are based on our present knowledge and are subject to change at any time due to technical requirements and development.

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